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What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "<u>Embedded -</u> <u>Microcontrollers</u>"

Details

Ξ·ΧΕΙ

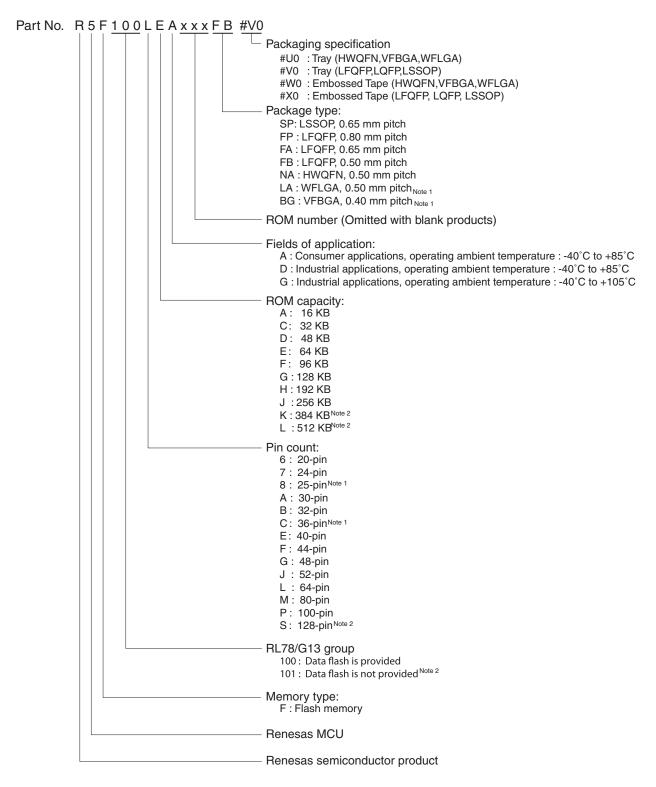
Product Status	Obsolete
Core Processor	RL78
Core Size	16-Bit
Speed	32MHz
Connectivity	CSI, I ² C, LINbus, UART/USART
Peripherals	DMA, LVD, POR, PWM, WDT
Number of I/O	48
Program Memory Size	64KB (64K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	4K x 8
Voltage - Supply (Vcc/Vdd)	1.6V ~ 5.5V
Data Converters	A/D 12x8/10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	64-LQFP
Supplier Device Package	64-LQFP (12x12)
Purchase URL	https://www.e-xfl.com/product-detail/renesas-electronics-america/r5f101leafa-v0

Email: info@E-XFL.COM

Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong

1.2 List of Part Numbers



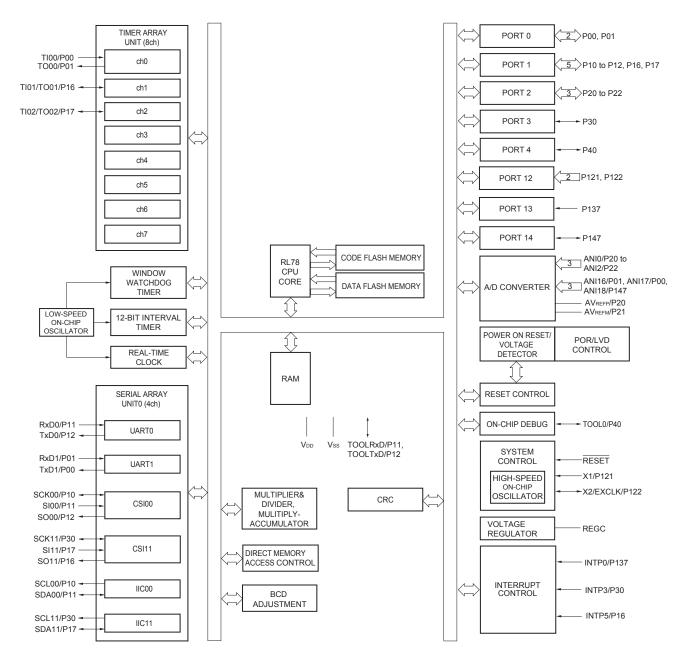


- **Notes** 1. Products only for "A: Consumer applications ($T_A = -40$ to $+85^{\circ}C$)", and "G: Industrial applications ($T_A = -40$ to $+105^{\circ}C$)"
 - **2.** Products only for "A: Consumer applications ($T_A = -40$ to $+85^{\circ}C$)", and "D: Industrial applications ($T_A = -40$ to $+85^{\circ}C$)"



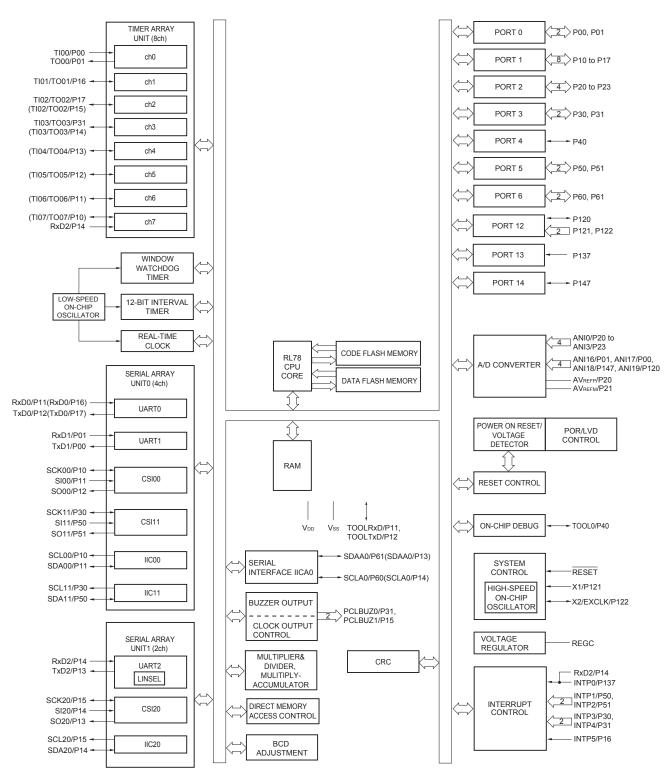
1.5 Block Diagram

1.5.1 20-pin products





1.5.4 30-pin products



Remark Functions in parentheses in the above figure can be assigned via settings in the peripheral I/O redirection register (PIOR). Refer to Figure 4-8 Format of Peripheral I/O Redirection Register (PIOR) in the RL78/G13 User's Manual.



 The number of PWM outputs varies depending on the setting of channels in use (the number of masters and slaves) (see 6.9.3 Operation as multiple PWM output function in the RL78/G13 User's Manual).

						1	(2/2)	
Ite	m	80-pin		100			3-pin	
		R5F100Mx R5	F101Mx	R5F100Px	R5F101Px	R5F100Sx	R5F101Sx	
Clock output/buzz	er output	2		:	2		2	
		 2.44 kHz, 4.88 kHz (Main system clock) 256 Hz, 512 Hz, 1.0 (Subsystem clock): 	: fmain = 20 024 kHz, 2.	MHz operation) .048 kHz, 4.096 k	Hz, 8.192 kHz, 1		68 kHz	
8/10-bit resolution	A/D converter	17 channels		20 channels		26 channels		
Serial interface		[80-pin, 100-pin, 128-	pin product	ts]				
		 CSI: 2 channels/sin 	nplified I ² C: nplified I ² C:	2 channels/UAR 2 channels/UAR	T: 1 channel T (UART suppor	ting LIN-bus): 1 c	channel	
	I ² C bus	2 channels		2 channels		2 channels		
Multiplier and divid	der/multiply-	• 16 bits × 16 bits = 32 bits (Unsigned or signed)						
accumulator		• 32 bits ÷ 32 bits = 32 bits (Unsigned)						
		• 16 bits × 16 bits + 32 bits = 32 bits (Unsigned or signed)						
DMA controller		4 channels						
Vectored	Internal	37		3	37			
interrupt sources	External	13		1	3	-	13	
Key interrupt	I	8		4	8		8	
Reset		 Reset by RESET pin Internal reset by watchdog timer Internal reset by power-on-reset Internal reset by voltage detector Internal reset by illegal instruction execution ^{Note} Internal reset by RAM parity error Internal reset by illegal-memory access 						
Power-on-reset ci	rcuit	 Power-on-reset: 1.51 V (TYP.) Power-down-reset: 1.50 V (TYP.) 						
Voltage detector		• Rising edge : 1.67 V to 4.06 V (14 stages) • Falling edge : 1.63 V to 3.98 V (14 stages)						
On-chip debug fur	nction	Provided						
Power supply voltage		$V_{_{DD}} = 1.6 \text{ to } 5.5 \text{ V} (T_{_A} = -40 \text{ to } +85^{\circ}\text{C})$ $V_{_{DD}} = 2.4 \text{ to } 5.5 \text{ V} (T_{_A} = -40 \text{ to } +105^{\circ}\text{C})$						
Operating ambien	t temperature	$T_A = 40$ to +85°C (A: Consumer applications, D: Industrial applications) $T_A = 40$ to +105°C (G: Industrial applications)						

<R>

Note The illegal instruction is generated when instruction code FFH is executed.

Reset by the illegal instruction execution not issued by emulation with the in-circuit emulator or on-chip debug emulator.



2. ELECTRICAL SPECIFICATIONS (TA = -40 to +85°C)

This chapter describes the following electrical specifications.

Target products A: Consumer applications $T_A = -40$ to $+85^{\circ}C$

R5F100xxAxx, R5F101xxAxx

- D: Industrial applications $T_A = -40$ to $+85^{\circ}C$ R5F100xxDxx, R5F101xxDxx
- G: Industrial applications when $T_A = -40$ to $+105^{\circ}$ C products is used in the range of $T_A = -40$ to $+85^{\circ}$ C

R5F100xxGxx

- Cautions 1. The RL78 microcontrollers have an on-chip debug function, which is provided for development and evaluation. Do not use the on-chip debug function in products designated for mass production, because the guaranteed number of rewritable times of the flash memory may be exceeded when this function is used, and product reliability therefore cannot be guaranteed. Renesas Electronics is not liable for problems occurring when the on-chip debug function is used.
 - 2. With products not provided with an EV_{DD0}, EV_{DD1}, EV_{SS0}, or EV_{SS1} pin, replace EV_{DD0} and EV_{DD1} with V_{DD}, or replace EV_{SS0} and EV_{SS1} with V_{SS}.
 - 3. The pins mounted depend on the product. Refer to 2.1 Port Function to 2.2.1 Functions for each product.

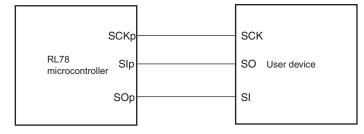


Items	Symbol	Conditions		MIN.	TYP.	MAX.	Unit
Input voltage, high	VIH1	P00 to P07, P10 to P17, P30 to P37, P40 to P47, P50 to P57, P64 to P67, P70 to P77, P80 to P87, P90 to P97, P100 to P106, P110 to P117, P120, P125 to P127, P140 to P147		0.8EVDD0		EVDDO	V
	VIH2	P01, P03, P04, P10, P11, P13 to P17, P43, P44, P53 to P55,	TTL input buffer $4.0 \text{ V} \leq \text{EV}_{\text{DD0}} \leq 5.5 \text{ V}$	2.2		EVDDO	V
		P80, P81, P142, P143	TTL input buffer $3.3 \text{ V} \leq \text{EV}_{\text{DD0}} < 4.0 \text{ V}$	2.0		EVDDO	V
			TTL input buffer $1.6 \text{ V} \leq \text{EV}_{\text{DD0}} < 3.3 \text{ V}$	1.5		EVDDO	V
	VIH3	P20 to P27, P150 to P156	0.7V _{DD}		VDD	V	
	VIH4	P60 to P63				6.0	V
	VIH5	P121 to P124, P137, EXCLK, EXCL	KS, RESET	0.8Vdd		VDD	V
Input voltage, low	VIL1	P00 to P07, P10 to P17, P30 to P37, P40 to P47, P50 to P57, P64 to P67, P70 to P77, P80 to P87, P90 to P97, P100 to P106, P110 to P117, P120, P125 to P127, P140 to P147		0		0.2EV _{DD0}	V
	VIL2	P01, P03, P04, P10, P11, P13 to P17, P43, P44, P53 to P55,	TTL input buffer 4.0 V \leq EV _{DD0} \leq 5.5 V	0		0.8	V
		P80, P81, P142, P143	TTL input buffer 3.3 V \leq EV _{DD0} $<$ 4.0 V	0		0.5	V
			TTL input buffer 1.6 V ≤ EV _{DD0} < 3.3 V	0		0.32	V
	VIL3	P20 to P27, P150 to P156	0		0.3Vdd	V	
	VIL4	P60 to P63		0		0.3EVDD0	V
	VIL5	P121 to P124, P137, EXCLK, EXCL	KS, RESET	0		0.2VDD	V

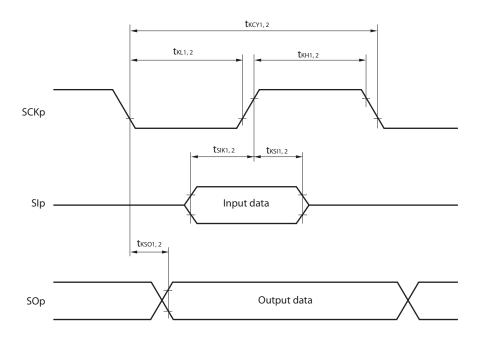
- Caution The maximum value of V_{IH} of pins P00, P02 to P04, P10 to P15, P17, P43 to P45, P50, P52 to P55, P71, P74, P80 to P82, P96, and P142 to P144 is EV_{DD0}, even in the N-ch open-drain mode.
- **Remark** Unless specified otherwise, the characteristics of alternate-function pins are the same as those of the port pins.



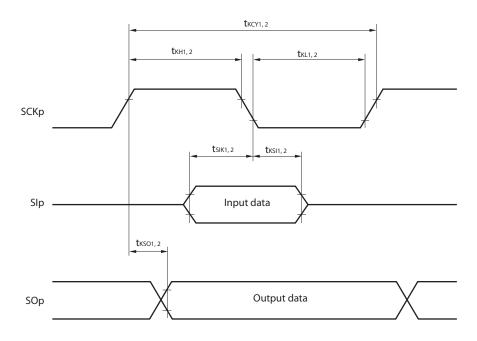
CSI mode connection diagram (during communication at same potential)

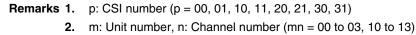


CSI mode serial transfer timing (during communication at same potential) (When DAPmn = 0 and CKPmn = 0, or DAPmn = 1 and CKPmn = 1.)



CSI mode serial transfer timing (during communication at same potential) (When DAPmn = 0 and CKPmn = 1, or DAPmn = 1 and CKPmn = 0.)







2.6 Analog Characteristics

2.6.1 A/D converter characteristics

Classification of A/D converter characteristics

		Reference Voltage								
	Reference voltage (+) = AVREFP	Reference voltage (+) = VDD	Reference voltage (+) = VBGR							
Input channel	Reference voltage (-) = AVREFM	Reference voltage (-) = Vss	Reference voltage (-) = AVREFM							
ANI0 to ANI14	Refer to 2.6.1 (1) .	Refer to 2.6.1 (3).	Refer to 2.6.1 (4) .							
ANI16 to ANI26	Refer to 2.6.1 (2) .									
Internal reference voltage	Refer to 2.6.1 (1) .		_							
Temperature sensor output										
voltage										

(1) When reference voltage (+)= AV_{REFP}/ANI0 (ADREFP1 = 0, ADREFP0 = 1), reference voltage (-) = AV_{REFM}/ANI1 (ADREFM = 1), target pin : ANI2 to ANI14, internal reference voltage, and temperature sensor output voltage

(T_A = -40 to +85°C, 1.6 V \leq AV_{REFP} \leq V_{DD} \leq 5.5 V, V_{SS} = 0 V, Reference voltage (+) = AV_{REFP}, Reference voltage (-) = AV_{REFM} = 0 V)

Parameter	Symbol	Conditions			TYP.	MAX.	Unit
Resolution	RES			8		10	bit
Overall error ^{Note 1}	AINL	10-bit resolution	$1.8~V \leq AV_{\text{REFP}} \leq 5.5~V$		1.2	±3.5	LSB
		$AV_{REFP} = V_{DD}{}^{Note 3}$	$1.6~V \leq AV_{\text{REFP}} \leq 5.5~V^{\text{Note 4}}$		1.2	±7.0	LSB
Conversion time	t CONV	10-bit resolution	$3.6~V \leq V \text{DD} \leq 5.5~V$	2.125		39	μS
		Target pin: ANI2 to	$2.7~V \leq V \text{DD} \leq 5.5~V$	3.1875		39	μS
		ANI14	$1.8~V \leq V \text{DD} \leq 5.5~V$	17		39	μS
			$1.6~V \leq V \text{DD} \leq 5.5~V$	57		95	μS
		10-bit resolution	$3.6~V \leq V \text{DD} \leq 5.5~V$	2.375		39	μS
		Target pin: Internal	$2.7~V \leq V \text{DD} \leq 5.5~V$	3.5625		39	μS
		reference voltage, and temperature sensor output voltage (HS (high-speed main) mode)	$2.4~V \leq V_{DD} \leq 5.5~V$	17		39	μs
Zero-scale error ^{Notes 1, 2}	Ezs	10-bit resolution	$1.8~V \leq AV_{\text{REFP}} \leq 5.5~V$			±0.25	%FSR
		$AV_{REFP} = V_{DD}^{Note 3}$	$1.6~V \leq AV_{\text{REFP}} \leq 5.5~V^{\text{Note 4}}$			±0.50	%FSR
Full-scale error ^{Notes 1, 2}	Ers	10-bit resolution	$1.8~V \leq AV_{\text{REFP}} \leq 5.5~V$			±0.25	%FSR
		$AV_{REFP} = V_{DD}^{Note 3}$	$1.6~V \leq AV_{\text{REFP}} \leq 5.5~V^{\text{Note 4}}$			±0.50	%FSR
Integral linearity error ^{Note 1}	ILE	10-bit resolution	$1.8~V \leq AV_{\text{REFP}} \leq 5.5~V$			±2.5	LSB
		$AV_{REFP} = V_{DD}{}^{Note 3}$	$1.6~V \leq AV_{\text{REFP}} \leq 5.5~V^{\text{Note 4}}$			±5.0	LSB
Differential linearity error Note 1	DLE	10-bit resolution	$1.8~V \leq AV_{\text{REFP}} \leq 5.5~V$			±1.5	LSB
		$AV_{REFP} = V_{DD}{}^{Note 3}$	$1.6~V \leq AV_{\text{REFP}} \leq 5.5~V^{\text{Note 4}}$			±2.0	LSB
Analog input voltage	VAIN	ANI2 to ANI14		0		AVREFP	V
		Internal reference voltage (2.4 V \leq VDD \leq 5.5 V, HS (high-speed main) mode)		VBGR Note 5			V
		Temperature sensor outp (2.4 V \leq VDD \leq 5.5 V, HS	0	VTMPS25 Note 5			V

(Notes are listed on the next page.)



(2) When reference voltage (+) = AV_{REFP}/ANI0 (ADREFP1 = 0, ADREFP0 = 1), reference voltage (-) = AV_{REFM}/ANI1 (ADREFM = 1), target pin : ANI16 to ANI26

$(T_{A} = -40 \text{ to } +85^{\circ}\text{C}, 1.6 \text{ V} \le \text{EV}_{\text{DD0}} = \text{EV}_{\text{DD1}} \le \text{V}_{\text{DD}} \le 5.5 \text{ V}, 1.6 \text{ V} \le \text{AV}_{\text{REFP}} \le \text{V}_{\text{DD}} \le 5.5 \text{ V}, \text{V}_{\text{SS}} = \text{EV}_{\text{SS0}} = \text{EV}_{\text{SS1}} = 0 \text{ V},$
Reference voltage (+) = AVREFP, Reference voltage (–) = AVREFM = 0 V)

Parameter	Symbol	Conditions			TYP.	MAX.	Unit
Resolution	RES			8		10	bit
Overall error ^{Note 1}	AINL	10-bit resolution	$1.8~V \leq AV_{\text{REFP}} \leq 5.5~V$		1.2	±5.0	LSB
		$EVDD0 = AV_{REFP} = V_{DD}^{Notes 3, 4}$	$1.6~V \leq AV_{REFP} \leq 5.5~V^{Note}$		1.2	±8.5	LSB
Conversion time	t CONV	10-bit resolution	$3.6~V \le V \text{DD} \le 5.5~V$	2.125		39	μs
		Target ANI pin : ANI16 to	$2.7~V \leq V \text{DD} \leq 5.5~V$	3.1875		39	μS
		ANI26	$1.8~V \leq V \text{DD} \leq 5.5~V$	17		39	μs
			$1.6~V \leq V \text{DD} \leq 5.5~V$	57		95	μS
Zero-scale error ^{Notes 1, 2}	Ezs 10-bit resolution EVDD0 = AVREFP = VD		$1.8~V \leq AV_{\text{REFP}} \leq 5.5~V$			±0.35	%FSR
		$EVDD0 = AV_{REFP} = V_{DD}$	$1.6~V \leq AV_{\text{REFP}} \leq 5.5~V^{\text{Note}}$			±0.60	%FSR
Full-scale error ^{Notes 1, 2}	EFS 10-bit resolution EVDD0 = AV _{REFP} = V _{DD} ^{Notes 3, 4}		$1.8~V \leq AV_{\text{REFP}} \leq 5.5~V$			±0.35	%FSR
		$1.6~V \leq AV_{REFP} \leq 5.5~V^{Note}$			±0.60	%FSR	
Integral linearity error ^{Note}	ILE	10-bit resolution	$1.8~V \leq AV_{\text{REFP}} \leq 5.5~V$			±3.5	LSB
1	$EVDD0 = AV_{REFP} = V_{DD}^{Notes 3, 4}$	$1.6~V \leq AV_{REFP} \leq 5.5~V^{Note}$			±6.0	LSB	
Differential linearity	DLE	10-bit resolution	$1.8~V \leq AV_{\text{REFP}} \leq 5.5~V$			±2.0	LSB
error Note 1	$EVDD0 = AV_{REFP} = V_{DD}^{Notes 3, 4}$	$1.6~V \leq AV_{REFP} \leq 5.5~V^{Note}$			±2.5	LSB	
Analog input voltage	VAIN	ANI16 to ANI26	·	0		AVREFP and EVDD0	V

Notes 1. Excludes quantization error ($\pm 1/2$ LSB).

- 2. This value is indicated as a ratio (%FSR) to the full-scale value.
- 3. When AV_{REFP} < V_{DD}, the MAX. values are as follows. Overall error: Add ± 1.0 LSB to the MAX. value when AV_{REFP} = V_{DD}. Zero-scale error/Full-scale error: Add $\pm 0.05\%$ FSR to the MAX. value when AV_{REFP} = V_{DD}. Integral linearity error/ Differential linearity error: Add ± 0.5 LSB to the MAX. value when AV_{REFP} = V_{DD}.
- 4. When AV_{REFP} < EV_{DD0} ≤ V_{DD}, the MAX. values are as follows. Overall error: Add ±4.0 LSB to the MAX. value when AV_{REFP} = V_{DD}. Zero-scale error/Full-scale error: Add ±0.20%FSR to the MAX. value when AV_{REFP} = V_{DD}. Integral linearity error/ Differential linearity error: Add ±2.0 LSB to the MAX. value when AV_{REFP} = V_{DD}.
- 5. When the conversion time is set to 57 μ s (min.) and 95 μ s (max.).



RL78/G13 3. ELECTRICAL SPECIFICATIONS (G: INDUSTRIAL APPLICATIONS TA = -40 to +105°C)

Remark The electrical characteristics of the products G: Industrial applications (T_A = -40 to +105°C) are different from those of the products "A: Consumer applications, and D: Industrial applications". For details, refer to 3.1 to 3.10.

3.1 Absolute Maximum Ratings

Parameter	Symbols	Conditions	Ratings	Unit
Supply voltage	VDD		–0.5 to +6.5	V
	EVDD0, EVDD1	EVDD0 = EVDD1	–0.5 to +6.5	V
	EVsso, EVss1	EVsso = EVss1	–0.5 to +0.3	V
REGC pin input voltage	VIREGC	REGC	-0.3 to +2.8 and -0.3 to V_{DD} +0.3 $^{\text{Note 1}}$	V
Input voltage	VI1	P00 to P07, P10 to P17, P30 to P37, P40 to P47,	-0.3 to EV _{DD0} +0.3	V
		P50 to P57, P64 to P67, P70 to P77, P80 to P87, P90 to P97, P100 to P106, P110 to P117, P120, P125 to P127, P140 to P147	and –0.3 to V_{DD} +0.3 ^{Note 2}	
	V _{I2}	P60 to P63 (N-ch open-drain)	-0.3 to +6.5	V
	Vı3	P20 to P27, P121 to P124, P137, P150 to P156, EXCLK, EXCLKS, RESET	-0.3 to V _{DD} +0.3 ^{Note 2}	V
Output voltage	Voi	P00 to P07, P10 to P17, P30 to P37, P40 to P47, P50 to P57, P60 to P67, P70 to P77, P80 to P87, P90 to P97, P100 to P106, P110 to P117, P120, P125 to P127, P130, P140 to P147		V
	V ₀₂	P20 to P27, P150 to P156	-0.3 to V _{DD} +0.3 ^{Note 2}	V
Analog input voltage	VAI1	ANI16 to ANI26	-0.3 to EV_DD0 +0.3 and -0.3 to AV_{REF}(+) +0.3 $^{\text{Notes 2, 3}}$	V
	Vai2	ANI0 to ANI14	-0.3 to V_DD +0.3 and -0.3 to AV_{REF}(+) +0.3^{Notes 2,3}	V

Absolute Maximum Ratings (T_A = 25°C) (1/2)

- **Notes 1.** Connect the REGC pin to Vss via a capacitor (0.47 to 1 μ F). This value regulates the absolute maximum rating of the REGC pin. Do not use this pin with voltage applied to it.
 - 2. Must be 6.5 V or lower.
 - **3.** Do not exceed AVREF(+) + 0.3 V in case of A/D conversion target pin.
- Caution Product quality may suffer if the absolute maximum rating is exceeded even momentarily for any parameter. That is, the absolute maximum ratings are rated values at which the product is on the verge of suffering physical damage, and therefore the product must be used under conditions that ensure that the absolute maximum ratings are not exceeded.
- **Remarks 1.** Unless specified otherwise, the characteristics of alternate-function pins are the same as those of the port pins.
 - **2.** $AV_{REF}(+)$: + side reference voltage of the A/D converter.
 - **3.** Vss : Reference voltage



Items	Symbol	Conditions		MIN.	TYP.	MAX.	Unit
Output current, low ^{Note 1}	Iol1	Per pin for P00 to P07, P10 to P17, P30 to P37, P40 to P47, P50 to P57, P64 to P67, P70 to P77, P80 to P87, P90 to P97, P100 to P106, P110 to P117, P120, P125 to P127, P130, P140 to P147				8.5 ^{Note 2}	mA
		Per pin for P60 to P63				15.0 ^{Note 2}	mA
		P37, P40 to P47, P102 to P106, P120,	$4.0~V \leq EV_{\text{DD0}} \leq 5.5~V$			40.0	mA
			$2.7~V \leq EV_{\text{DD0}} < 4.0~V$			15.0	mA
			$2.4~V \leq EV_{DD0} < 2.7~V$			9.0	mA
		Total of P05, P06, P10 to P17, P30,	$4.0~V \leq EV_{\text{DD0}} \leq 5.5~V$			40.0	mA
			$2.7~V \leq EV_{\text{DD0}} < 4.0~V$			35.0	mA
		P70 to P77, P80 to P87, P90 to P97, P100, P101, P110 to P117, P146, P147 (When duty $\leq 70\%$ ^{Note 3})	$2,4~V \leq EV_{\text{DD0}} < 2.7~V$			20.0	mA
		Total of all pins (When duty $\leq 70\%$ ^{Note 3})				80.0	mA
	IOL2	Per pin for P20 to P27, P150 to P156				0.4 Note 2	mA
		Total of all pins (When duty $\leq 70\%^{Note 3}$)	$2,4~V \leq V_{\text{DD}} \leq 5.5~V$			5.0	mA

$(T_A = -40 \text{ to } +105^{\circ}\text{C}, 2.4 \text{ V} \le \text{EV}_{\text{DD0}} = \text{EV}_{\text{DD1}} \le \text{V}_{\text{DD}} \le 5.5 \text{ V}, \text{ Vss} = \text{EV}_{\text{SS0}} = \text{EV}_{\text{SS1}} = 0 \text{ V})$ (2/5)

- **Notes 1**. Value of current at which the device operation is guaranteed even if the current flows from an output pin to the EVsso, EVss1 and Vss pin.
 - 2. Do not exceed the total current value.
 - **3.** Specification under conditions where the duty factor \leq 70%.

The output current value that has changed to the duty factor > 70% the duty ratio can be calculated with the following expression (when changing the duty factor from 70% to n%).

• Total output current of pins = $(I_{OL} \times 0.7)/(n \times 0.01)$

<Example> Where n = 80% and $I_{OL} = 10.0 \text{ mA}$

Total output current of pins = $(10.0 \times 0.7)/(80 \times 0.01) \cong 8.7 \text{ mA}$

However, the current that is allowed to flow into one pin does not vary depending on the duty factor. A current higher than the absolute maximum rating must not flow into one pin.

Remark Unless specified otherwise, the characteristics of alternate-function pins are the same as those of the port pins.



Items	Symbol	Conditions		MIN.	TYP.	MAX.	Unit
Input voltage, high	VIH1	P00 to P07, P10 to P17, P30 to P37, P40 to P47, P50 to P57, P64 to P67, P70 to P77, P80 to P87, P90 to P97, P100 to P106, P110 to P117, P120, P125 to P127, P140 to P147	·	0.8EV _{DD0}		EVDDO	V
	VIH2	P01, P03, P04, P10, P11, P13 to P17, P43, P44, P53 to P55,	TTL input buffer $4.0 \text{ V} \leq \text{EV}_{\text{DD0}} \leq 5.5 \text{ V}$	2.2		EVDD0	V
		P80, P81, P142, P143	TTL input buffer $3.3 \text{ V} \leq \text{EV}_{\text{DD0}} < 4.0 \text{ V}$	2.0		EVDD0	V
			TTL input buffer $2.4 \text{ V} \leq EV_{\text{DD0}} < 3.3 \text{ V}$	1.5		EVDDO	V
	VIH3	P20 to P27, P150 to P156	0.7V _{DD}		VDD	V	
	VIH4	P60 to P63	0.7EVDD0		6.0	V	
	VIH5	P121 to P124, P137, EXCLK, EXCLKS, RESET				VDD	V
Input voltage, Iow	VIL1	P00 to P07, P10 to P17, P30 to P37, P40 to P47, P50 to P57, P64 to P67, P70 to P77, P80 to P87, P90 to P97, P100 to P106, P110 to P117, P120, P125 to P127, P140 to P147		0		0.2EV _{DD0}	V
	VIL2	P01, P03, P04, P10, P11, P13 to P17, P43, P44, P53 to P55,	TTL input buffer 4.0 V \leq EV _{DD0} \leq 5.5 V	0		0.8	V
		P80, P81, P142, P143	TTL input buffer 3.3 V ≤ EV _{DD0} < 4.0 V	0		0.5	V
			TTL input buffer 2.4 V \leq EV _{DD0} $<$ 3.3 V	0		0.32	V
	VIL3	P20 to P27, P150 to P156		0		0.3VDD	V
	VIL4	P60 to P63		0		0.3EVDD0	V
	VIL5	P121 to P124, P137, EXCLK, EXCLK	(S, RESET	0		0.2VDD	V

 $(T_A = -40 \text{ to } +105^{\circ}\text{C}, 2.4 \text{ V} \le \text{EV}_{DD0} = \text{EV}_{DD1} \le \text{V}_{DD} \le 5.5 \text{ V}, \text{ V}_{SS} = \text{EV}_{SS0} = \text{EV}_{SS1} = 0 \text{ V})$ (3/5)

- Caution The maximum value of V_{IH} of pins P00, P02 to P04, P10 to P15, P17, P43 to P45, P50, P52 to P55, P71, P74, P80 to P82, P96, and P142 to P144 is EV_{DD0}, even in the N-ch open-drain mode.
- **Remark** Unless specified otherwise, the characteristics of alternate-function pins are the same as those of the port pins.



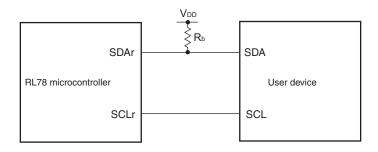
- **Notes 1.** Total current flowing into VDD, EVDDD, and EVDD1, including the input leakage current flowing when the level of the input pin is fixed to VDD, EVDDD, and EVDD1, or Vss, EVSSD, and EVSS1. The values below the MAX. column include the peripheral operation current. However, not including the current flowing into the A/D converter, LVD circuit, I/O port, and on-chip pull-up/pull-down resistors and the current flowing during data flash rewrite.
 - 2. During HALT instruction execution by flash memory.
 - 3. When high-speed on-chip oscillator and subsystem clock are stopped.
 - 4. When high-speed system clock and subsystem clock are stopped.
 - When high-speed on-chip oscillator and high-speed system clock are stopped. When RTCLPC = 1 and setting ultra-low current consumption (AMPHS1 = 1). The current flowing into the RTC is included. However, not including the current flowing into the 12-bit interval timer and watchdog timer.
 - 6. Not including the current flowing into the RTC, 12-bit interval timer, and watchdog timer.
 - 7. Relationship between operation voltage width, operation frequency of CPU and operation mode is as below.

HS (high-speed main) mode: 2.7 V \leq V_DD \leq 5.5 V@1 MHz to 32 MHz 2.4 V \leq V_DD \leq 5.5 V@1 MHz to 16 MHz

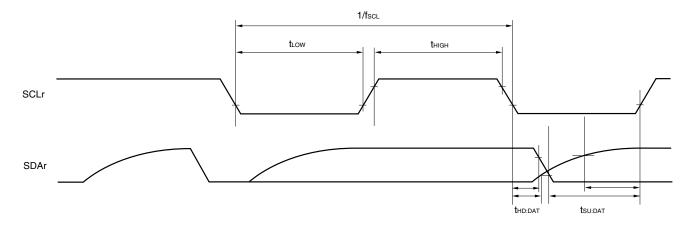
- 8. Regarding the value for current operate the subsystem clock in STOP mode, refer to that in HALT mode.
- **Remarks 1.** fmx: High-speed system clock frequency (X1 clock oscillation frequency or external main system clock frequency)
 - 2. file: High-speed on-chip oscillator clock frequency
 - 3. fsub: Subsystem clock frequency (XT1 clock oscillation frequency)
 - 4. Except subsystem clock operation and STOP mode, temperature condition of the TYP. value is $T_A = 25^{\circ}C$



Simplified I²C mode mode connection diagram (during communication at same potential)



Simplified I²C mode serial transfer timing (during communication at same potential)



- **Remarks 1.** R_b[Ω]:Communication line (SDAr) pull-up resistance, C_b[F]: Communication line (SDAr, SCLr) load capacitance
 - r: IIC number (r = 00, 01, 10, 11, 20, 21, 30, 31), g: PIM number (g = 0, 1, 4, 5, 8, 14),
 h: POM number (g = 0, 1, 4, 5, 7 to 9, 14)
 - 3. fmck: Serial array unit operation clock frequency

(Operation clock to be set by the CKSmn bit of serial mode register mn (SMRmn). m: Unit number (m

= 0, 1), n: Channel number (n = 0 to 3), mn = 00 to 03, 10 to 13)



5. The smaller maximum transfer rate derived by using fMCK/12 or the following expression is the valid maximum transfer rate.

Expression for calculating the transfer rate when 2.4 V \leq EVDD0 < 3.3 V and 1.6 V \leq Vb \leq 2.0 V

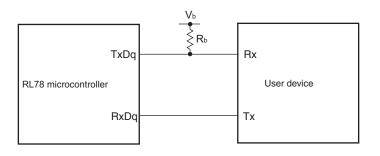
Maximum transfer rate =
$$\frac{1}{\{-C_b \times R_b \times \ln (1 - \frac{1.5}{V_b})\} \times 3}$$
 [bps]

Baud rate error (theoretical value) = $\frac{\frac{1}{\text{Transfer rate} \times 2} - \{-C_b \times R_b \times \ln(1 - \frac{1.5}{V_b})\}}{(\frac{1}{\text{Transfer rate}}) \times \text{Number of transferred bits}} \times 100 [\%]$

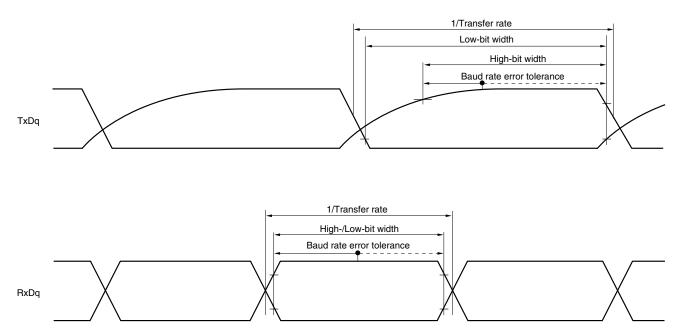
* This value is the theoretical value of the relative difference between the transmission and reception sides.

- **6.** This value as an example is calculated when the conditions described in the "Conditions" column are met. Refer to Note 5 above to calculate the maximum transfer rate under conditions of the customer.
- Caution Select the TTL input buffer for the RxDq pin and the N-ch open drain output (V_{DD} tolerance (for the 20- to 52-pin products)/EV_{DD} tolerance (for the 64- to 100-pin products)) mode for the TxDq pin by using port input mode register g (PIMg) and port output mode register g (POMg). For V_{IH} and V_{IL}, see the DC characteristics with TTL input buffer selected.

UART mode connection diagram (during communication at different potential)







UART mode bit width (during communication at different potential) (reference)

 Remarks 1.
 Rb[Ω]:Communication line (TxDq) pull-up resistance,

 Cb[F]: Communication line (TxDq) load capacitance, Vb[V]: Communication line voltage

- **2.** q: UART number (q = 0 to 3), g: PIM and POM number (g = 0, 1, 8, 14)
- 3. fmck: Serial array unit operation clock frequency

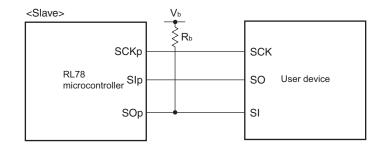
(Operation clock to be set by the CKSmn bit of serial mode register mn (SMRmn). m: Unit number, n: Channel number (mn = 00 to 03, 10 to 13))

4. UART2 cannot communicate at different potential when bit 1 (PIOR1) of peripheral I/O redirection register (PIOR) is 1.



- **Notes 1.** Transfer rate in the SNOOZE mode : MAX. 1 Mbps
 - 2. When DAPmn = 0 and CKPmn = 0, or DAPmn = 1 and CKPmn = 1. The SIp setup time becomes "to SCKp↓" when DAPmn = 0 and CKPmn = 1, or DAPmn = 1 and CKPmn = 0.
 - 3. When DAPmn = 0 and CKPmn = 0, or DAPmn = 1 and CKPmn = 1. The SIp hold time becomes "from SCKp↓" when DAPmn = 0 and CKPmn = 1, or DAPmn = 1 and CKPmn = 0.
 - **4.** When DAPmn = 0 and CKPmn = 0, or DAPmn = 1 and CKPmn = 1. The delay time to SOp output becomes "from SCKp[↑]" when DAPmn = 0 and CKPmn = 1, or DAPmn = 1 and CKPmn = 0.
- Caution Select the TTL input buffer for the SIp pin and SCKp pin and the N-ch open drain output (V_{DD} tolerance (for the 20- to 52-pin products)/EV_{DD} tolerance (for the 64- to 128-pin products)) mode for the SOp pin by using port input mode register g (PIMg) and port output mode register g (POMg). For V_H and V_L, see the DC characteristics with TTL input buffer selected.

CSI mode connection diagram (during communication at different potential)



- **Remarks 1.** R_b[Ω]:Communication line (SOp) pull-up resistance, C_b[F]: Communication line (SOp) load capacitance, V_b[V]: Communication line voltage
 - p: CSI number (p = 00, 01, 10, 20, 30, 31), m: Unit number (m = 0, 1), n: Channel number (n = 00, 01, 02,

10, 12, 13), g: PIM and POM number (g = 0, 1, 4, 5, 8, 14)

3. fMCK: Serial array unit operation clock frequency

(Operation clock to be set by the CKSmn bit of serial mode register mn (SMRmn).

m: Unit number, n: Channel number (mn = 00, 01, 02, 10, 12, 13))

4. CSI01 of 48-, 52-, 64-pin products, and CSI11 and CSI21 cannot communicate at different potential. Use other CSI for communication at different potential.

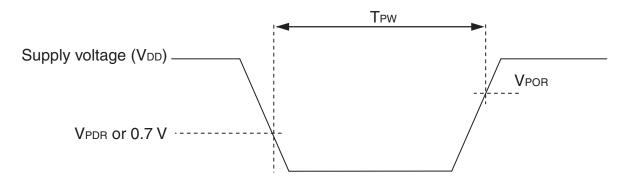


3.6.3 POR circuit characteristics

$(T_A = -40 \text{ to } +105^{\circ}\text{C}, \text{ Vss} = 0 \text{ V})$

Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Detection voltage	VPOR	Power supply rise time	1.45	1.51	1.57	V
	VPDR	Power supply fall time	1.44	1.50	1.56	V
Minimum pulse width	TPW		300			μs

Note Minimum time required for a POR reset when V_{DD} exceeds below V_{PDR}. This is also the minimum time required for a POR reset from when V_{DD} exceeds below 0.7 V to when V_{DD} exceeds V_{POR} while STOP mode is entered or the main system clock is stopped through setting bit 0 (HIOSTOP) and bit 7 (MSTOP) in the clock operation status control register (CSC).

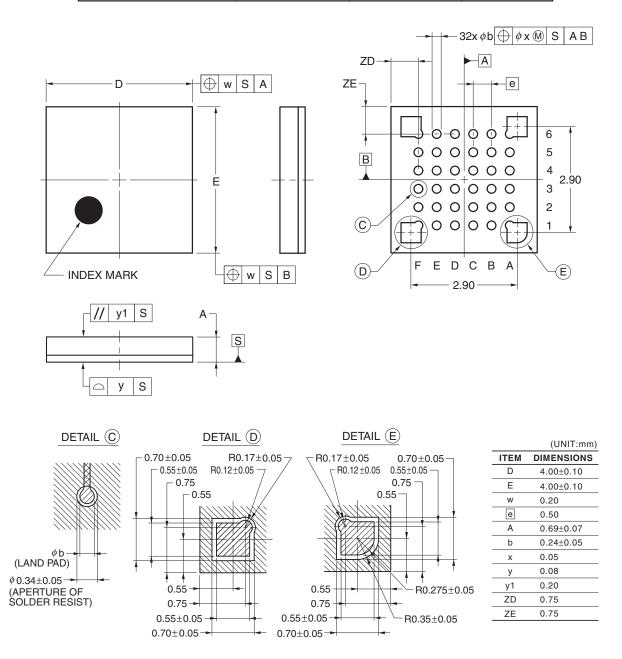




4.6 36-pin Products

R5F100CAALA, R5F100CCALA, R5F100CDALA, R5F100CEALA, R5F100CFALA, R5F100CGALA R5F101CAALA, R5F101CCALA, R5F101CDALA, R5F101CEALA, R5F101CFALA, R5F101CGALA R5F100CAGLA, R5F100CCGLA, R5F100CDGLA, R5F100CEGLA, R5F100CFGLA, R5F100CGGLA

JEITA Package Code	RENESAS Code	Previous Code	MASS (TYP.) [g]
P-WFLGA36-4x4-0.50	PWLG0036KA-A	P36FC-50-AA4-2	0.023



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Rev.	Date	Description		
		Page	Summary	
3.00	Aug 02, 2013	163	Modification of table in (8) Communication at different potential (1.8 V, 2.5 V, 3 V) (simplified I^2C mode) (1/2)	
		164, 165	Modification of table, note 1, and caution in (8) Communication at different potential (1.8 V, 2.5 V, 3 V) (simplified I ² C mode) (2/2)	
		166	Modification of table in 3.5.2 Serial interface IICA	
		166	Modification of IICA serial transfer timing	
		167	Addition of table in 3.6.1 A/D converter characteristics	
		167, 168	Modification of table and notes 3 and 4 in 3.6.1 (1)	
		169	Modification of description in 3.6.1 (2)	
		170	Modification of description and note 3 in 3.6.1 (3)	
		171	Modification of description and notes 3 and 4 in 3.6.1 (4)	
		172	Modification of table and note in 3.6.3 POR circuit characteristics	
		173	Modification of table of LVD Detection Voltage of Interrupt & Reset Mode	
		173	Modification from Supply Voltage Rise Time to 3.6.5 Power supply voltage rising slope characteristics	
		174	Modification of 3.9 Dedicated Flash Memory Programmer Communication (UART)	
		175	Modification of table, figure, and remark in 3.10 Timing Specs for Switching Flash Memory Programming Modes	
3.10	Nov 15, 2013	123	Caution 4 added.	
		125	Note for operating ambient temperature in 3.1 Absolute Maximum Ratings deleted.	
3.30	Mar 31, 2016		Modification of the position of the index mark in 25-pin plastic WFLGA (3×3 mm, 0.50 mm pitch) of 1.3.3 25-pin products	
			Modification of power supply voltage in 1.6 Outline of Functions [20-pin, 24- pin, 25-pin, 30-pin, 32-pin, 36-pin products]	
			Modification of power supply voltage in 1.6 Outline of Functions [40-pin, 44- pin, 48-pin, 52-pin, 64-pin products]	
			Modification of power supply voltage in 1.6 Outline of Functions [80-pin, 100- pin, 128-pin products]	
			ACK corrected to ACK	
			ACK corrected to ACK	

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